

## EAST Search History

| Ref # | Hits   | Search Query  | DBs  | Default Operator | Plurals | Time Stamp          |
|-------|--------|---|--|------------------|---------|---------------------|
| L1    | 4      | "2003052404"  | US-PGPUB;<br>USPAT; USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/06/23<br>12:43 |
| L2    | 2      | "20030052404"   | US-PGPUB;<br>USPAT; USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/06/23<br>12:43 |
| L3    | 655759 | (lead leadframe multilayer (multi adj (metal trace wiring layer))) with (edge border expos\$4 end bottom surface) | US-PGPUB;<br>USPAT; USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/06/23<br>13:15 |
| L4    | 28648  | (anchor\$4 indent\$4 groove concav\$4) with 3   | US-PGPUB;<br>USPAT; USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/06/23<br>13:16 |
| L5    | 3289   | 4 with (insulat\$4 epoxy encapsulat\$\$ encase resin)   | US-PGPUB;<br>USPAT; USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/06/23<br>13:36 |
| L6    | 2623   | (hole thru through throughhole via opening) and 5   | US-PGPUB;<br>USPAT; USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/06/23<br>13:37 |
| L7    | 1346   | (flipchip (flip adj chip) semiconductor electronic die chip ) and 6   | US-PGPUB;<br>USPAT; USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/06/23<br>13:39 |

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